

# AM2371P-VB Datasheet

# P-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
- 100	0.50 at V <sub>GS</sub> = - 10 V	- 1.5	7.7		
- 100	0.56 at V <sub>GS</sub> = - 6.0 V	- 1.4	7.7		

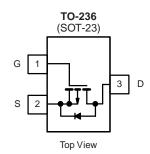
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET<sup>®</sup> Power MOSFET
- Ultra Low On-Resistance
- Small Size



#### **APPLICATIONS**

• Active Clamp Circuits in DC/DC Power Supplies



ABSOLUTE MAXIMUM RATINGS	T <sub>A</sub> = 25 °C, unle	ss otherwise r	noted		
Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		V <sub>DS</sub>	- 100		V
Gate-Source Voltage		$V_{GS}$	± 20		V
Continuous Desir Courset /T 450 °C) a b	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 1.65	- 1.5	
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a, b</sup>	T <sub>A</sub> = 70 °C		- 1.55	- 1.4	
Pulsed Drain Current		I <sub>DM</sub>	- 3.0		Α
Continuous Source Current (Diode Conduction) <sup>a, b</sup>		I <sub>S</sub>	- 1.4	- 1.0	
Single Pulse Avalanche Current		I <sub>AS</sub>	4.5		
Single Pulse Avalanche Energy	L = 1.0 mn	L = 1.0 mH E <sub>AS</sub>		1.01	
Mariana Barra Birata di Ab	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.0	0.85	W
Maximum Power Dissipation <sup>a, b</sup>	T <sub>A</sub> = 70 °C		1.0	0.58	
Operating Junction and Storage Temperature Ran	T <sub>J</sub> , T <sub>stg</sub>	- 55	to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Marrian Innerticut to Ambient	t ≤5 s	R <sub>thJA</sub>	75	100	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	¹`thJA	120	166	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	40	50	

#### Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.



			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 100			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 3.0	, v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	1	V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 0 V			- 1	uA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -15 \text{ V}, V_{GS} = 10 \text{ V}$	- 1.6			Α	
		$V_{GS} = -10 \text{ V}, I_D = -0.5 \text{ A}$		0.50	0.50	0	
Drain-Source On-Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 6.0 V, I <sub>D</sub> = - 0.5 A		0.56		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 0.5 A		2.2		S	
Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> = - 1.0 A, V <sub>GS</sub> = 0 V		0.7	- 1.2	V	
Dynamic <sup>b</sup>	•		•	•			
Total Gate Charge	$Q_g$	V - 50VV - 10V		7.7	12		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -50 \text{ V}, V_{GS} = 10 \text{ V},$ $I_{D} \cong -0.5 \text{ A}$		1.5		nC	
Gate-Drain Charge	$Q_{gd}$	1D = - 0.0 A		2.5			
Gate Resistance	$R_g$	f = 1.0 MHz		9		Ω	
Input Capacitance	C <sub>iss</sub>			520			
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		40		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			20		1	
Switching <sup>c</sup>							
Turn-On Time	t <sub>d(on)</sub>	V 50 V D 75 C		7	11		
Turn-On Time	t <sub>r</sub>	$V_{DD} = -50 \text{ V}, R_{L} = 75 \Omega$ $I_{D} \cong -1.0 \text{ A}, V_{GEN} = -10 \text{ V}$		11	17	ne	
Turn-Off Time	t <sub>d(off)</sub>	$R_{\alpha} = 6 \Omega$		16	25	ns	
Turn-On Time	t <sub>f</sub>	. ·y =		11	17		
Body Diode Reverse Recovery Charge $Q_{rr}$ $I_F = 0.5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$		$I_F = 0.5 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}$		90	135	nC	

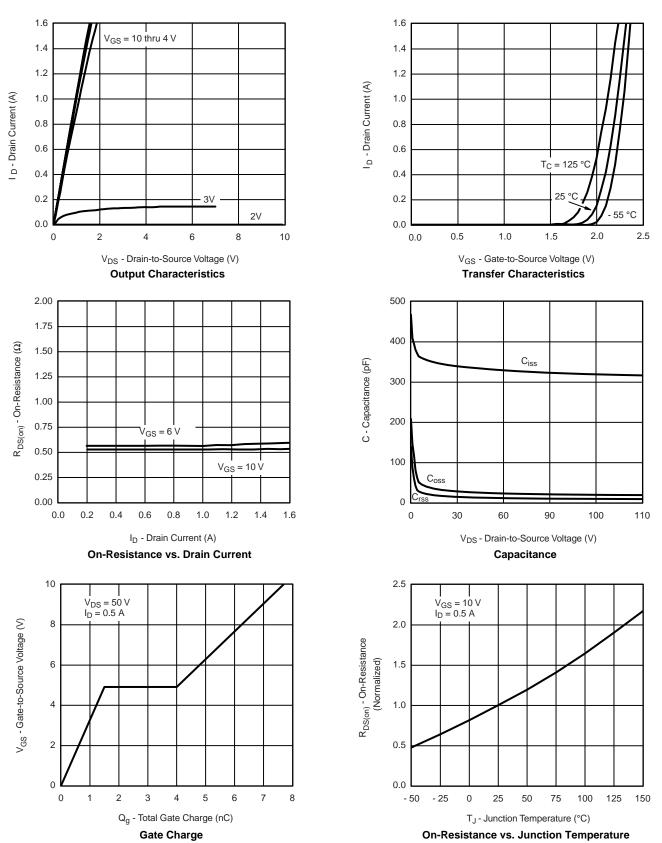
#### Notes:

- a. Pulse test: PW  $\leq 300~\mu s$  duty cycle  $\leq 2~\%.$
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

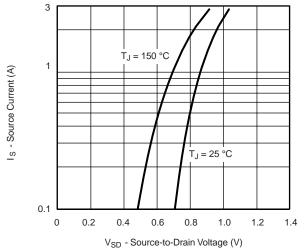


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

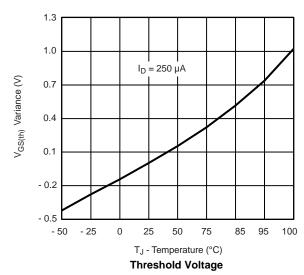


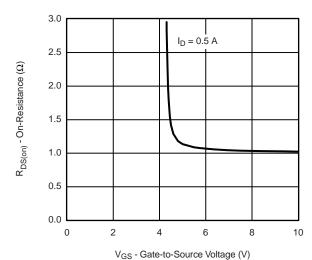


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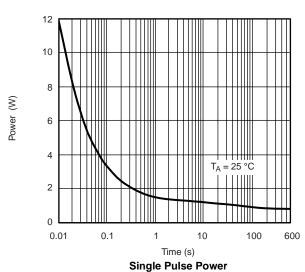


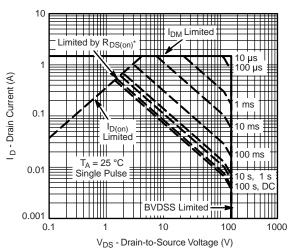
### Source-Drain Diode Forward Voltage





On-Resistance vs. Gate-to-Source Voltage



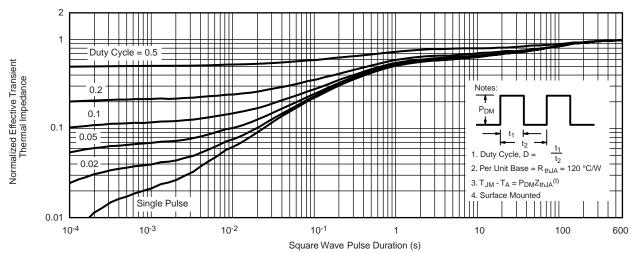


\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area



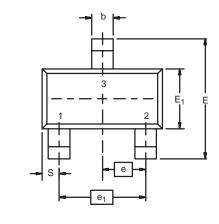
# **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

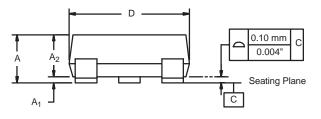


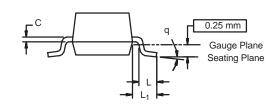
Normalized Thermal Transient Impedance, Junction-to-Ambient



# SOT-23 (TO-236): 3-LEAD







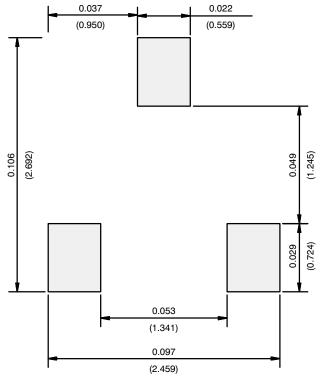
Dim -	MILLIMETERS		INCHES			
	Min	Max	Min	Max		
Α	0.89	1.12	0.035	0.044		
A <sub>1</sub>	0.01	0.10	0.0004	0.004		
A <sub>2</sub>	0.88	1.02	0.0346	0.040		
b	0.35	0.50	0.014	0.020		
С	0.085	0.18	0.003	0.007		
D	2.80	3.04	0.110	0.120		
E	2.10	2.64	0.083	0.104		
E <sub>1</sub>	1.20	1.40	0.047	0.055		
е	0.95 BSC		0.0374 Ref			
e <sub>1</sub>	1.90 BSC		0.074	0.0748 Ref		
L	0.40	0.60	0.016	0.024		
L <sub>1</sub>	0.64 Ref		0.025	5 Ref		
S	0.50 Ref		0.020	0.020 Ref		
q	3°	8°	3°	8°		

DWG: 5479

6



## **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

服务热线:400-655-8788 Á 7



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